

REMARKS

Claims 1, 11 and 26 have been amended without any intention of narrowing the scope of the claims. Claim 32 has been added. Claims 1-32 are presently pending. Reconsideration and allowance of the present claims based on the following remarks are respectfully requested.

Claims 1-31 were rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by U.S. Patent No. 6,191,429 to Suwa ("Suwa"). Applicant traverses this rejection for at least the following reasons.

Applicant submits that the cited portions of Suwa fail to disclose or teach a lithographic apparatus comprising, *inter alia*, a mask table configured to hold a mask, the mask configured to impart the beam with a pattern, said mask table being configured to receive said mask at least two positions displaced in a first direction so that at least a different part of the mask table comes into contact with the mask at each of the at least two positions and so that different parts of the pattern on the mask can be brought within an exposure field when the mask is in different ones of said positions, as recited in claim 1, or a device manufacturing method comprising, *inter alia*, using a mask to impart a beam of radiation with a pattern, wherein said mask is positioned on a mask table at a first position to image a first portion of the pattern of said mask and is subsequently positioned on said mask table at a second position to image a second portion of said pattern, wherein the mask at the second position is in contact with at least a different part of the mask table than at the first position, as recited in claim 11.

For example, the cited portion of Suwa disclose a scanning lithographic apparatus, where shot areas SAa, SAB on the wafer W are irradiated by scanning a pattern Pa on the reticle R through the projection beam in a given direction while scanning the wafer W in the opposite direction. *See* col. 11, lines 4-39 of Suwa. Further, Suwa discloses that the reticle R is supported on a reticle stage 14 by vacuum suction attraction and that the reticle stage 14 can move at a constant speed in one dimension with a large stroke during scanning exposure. *See* col. 8, lines 29-31 of Suwa. It appears, however, that the reticle R of Suwa is provided at, and remains in, a single same position on and with respect to the reticle stage 14. *See* Figure 1 of Suwa. Indeed, the cited portions of Suwa make no mention or suggestion that the mask table is configured to receive that mask at a first position and at least a second position so that at least a different part

of the mask table comes into contact with the mask at each of the at least two positions and so that different portions of the pattern on the mask can be imaged when the mask is in the first position and the second position. At most, Applicant submits that the cited portions of Suwa disclose a mask table that receives the mask at a first position on the mask table during exposure (and the arrow in Figure 2 shows the motion of the mask once on the mask table at that first and only position), but not at least a second position as claimed where, for example, the mask is in contact with at least a different part of the mask table than when in the first position.

With respect to claim 26, it appears that the same portion, i.e., entire pattern Pa, on the reticle R of Suwa is scanned onto each of the spatially separated shot areas SAa, SAb on the wafer W. *See* Figure 2 and col. 11, lines 37-40 of Suwa (“In accordance with the above-described schedule, a plurality of shot areas on the wafer W are exposed to the image of the circuit pattern area Pa of the reticle R.”). Thus, the cited portion of Suwa make no mention or suggestion of an apparatus configured to position the mask such that a first portion of said mask is projected during a first scanning motion onto a first portion of the substrate and a second different portion of said mask is projected during a second subsequent scanning motion onto a second portion of the substrate abutting or overlapping the first portion of the substrate as recited in claim 26. Rather, the cited portions of Suwa merely disclose a single first portion of the reticle R, i.e., entire pattern Pa, that is scanned onto the wafer W and further that first portion of the reticle R is exposed onto spatially separated shot areas SAa, SAb that neither abut nor overlap each other.

Accordingly, Applicant submits that a case of anticipation has not been established and that the cited portions of Suwa do not disclose or teach each and every feature recited by claims 1, 11 and 26. Claims 2-10, 12-25 and 27-31 depend respectively from claims 1, 11 and 26 and are, therefore, patentable for at least the same reasons provided above related to claims 1, 11 and 26 respectively, and for the additional features recited therein. Thus, Applicant respectfully requests that the rejections of claims 1-31 under 35 U.S.C. § 102(b) over Suwa should be withdrawn and the claims be allowed.

New claim 32 is added to define additional subject matter that is novel and non-obvious and finds support in the application as filed. Claim 32 is patentable over the applied art of record

at least by virtue of its dependency from claim 26, and for the additional features recited therein. Accordingly, claim 32 is in condition for allowance.

All matters having been addressed and in view of the foregoing, Applicant respectfully requests the entry of this Amendment, the Examiner's reconsideration of this application, and the immediate allowance of all pending claims.

Applicant's representative remains ready to assist the Examiner in any way to facilitate and expedite the prosecution of this matter. If any point remains in issue which the Examiner feels may be best resolved through a personal or telephone interview, please contact the undersigned at the telephone number listed below.

Please charge any fees associated with the submission of this paper to Deposit Account Number 033975. The Commissioner for Patents is also authorized to credit any over payments to the above-referenced Deposit Account.

Respectfully submitted,


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